

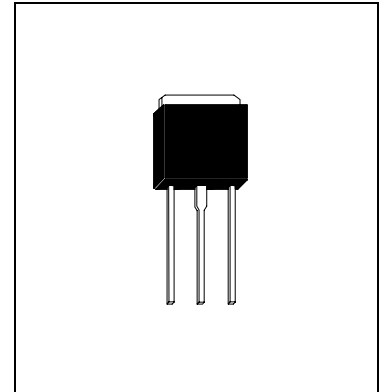


HI127

PNP EPITAXIAL PLANAR TRANSISTOR

Description

- High DC current gain
- Built-in a damper diode at E-C



Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
 Storage Temperature -55 ~ +150 °C
 Junction Temperature +150 °C
- Maximum Power Dissipation
 Total Power Dissipation (Tc=25°C) 20W
- Maximum Voltages and Currents
 BVCBO Collector to Base Voltage -100 V
 BVCEO Collector to Emitter Voltage -100 V
 BVEBO Emitter to Base Voltage -5 V
 IC Collector Current -8 A

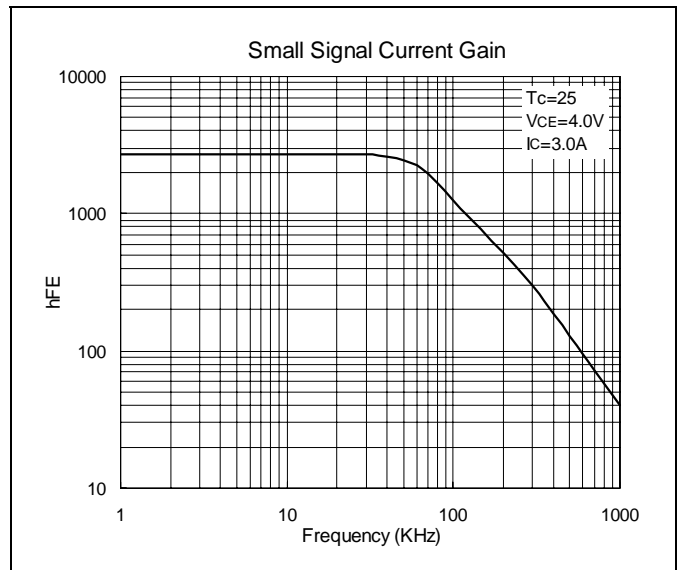
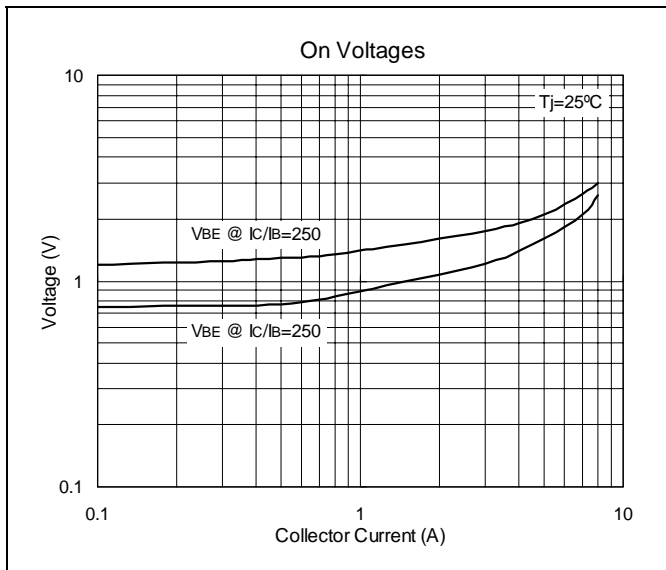
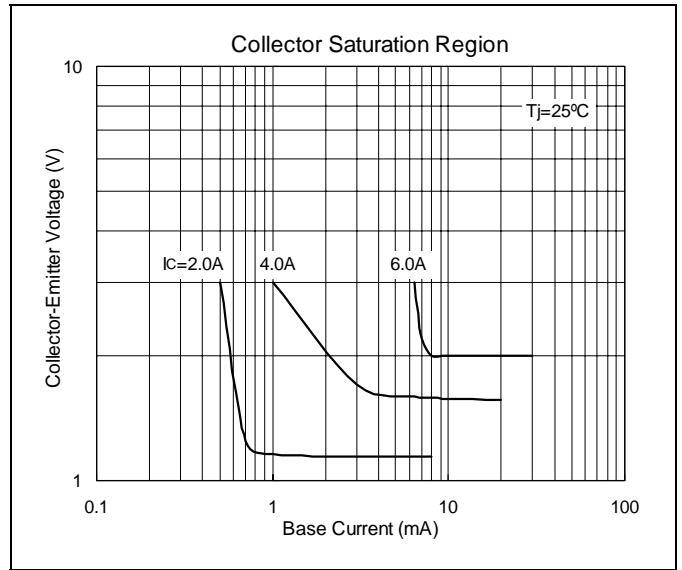
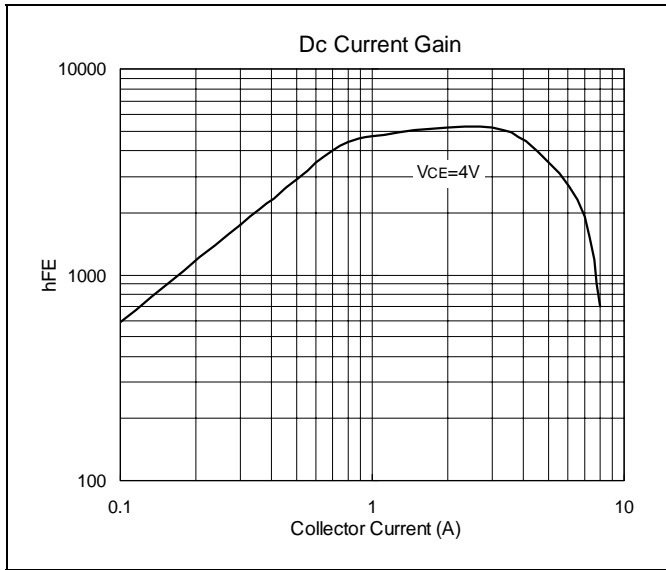
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-100	-	-	V	IC=-1mA, IE=0
BVCEO	-100	-	-	V	IC=-30mA, IB=0
BVEBO	-5	-	-	V	IE=-1mA, IC=0
ICBO	-	-	-10	uA	VCB=-100V, IE=0
IEBO	-	-	-2	mA	VEB=-5V, IC=0
ICEX	-	-	-10	uA	VCE=-100V, VBE(off)=-1.5V
*VCE(sat)1	-	-	-2	V	IC=-4A, IB=-16mA
*VCE(sat)2	-	-	-4	V	IC=-8A, IB=-80mA
*VBE(sat)	-	-	-4.5	V	IC=-8A, IB=-80mA
*VBE(on)	-	-	-2.8	V	VCE=-4V, IC=-4A
*hFE1	1	-	12	K	VCE=-4V, IC=-4A
*hFE2	100	-	-		VCE=-4V, IC=-8A
Cob	-	-	300	pF	VCB=-10V, f=0.1MHz

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

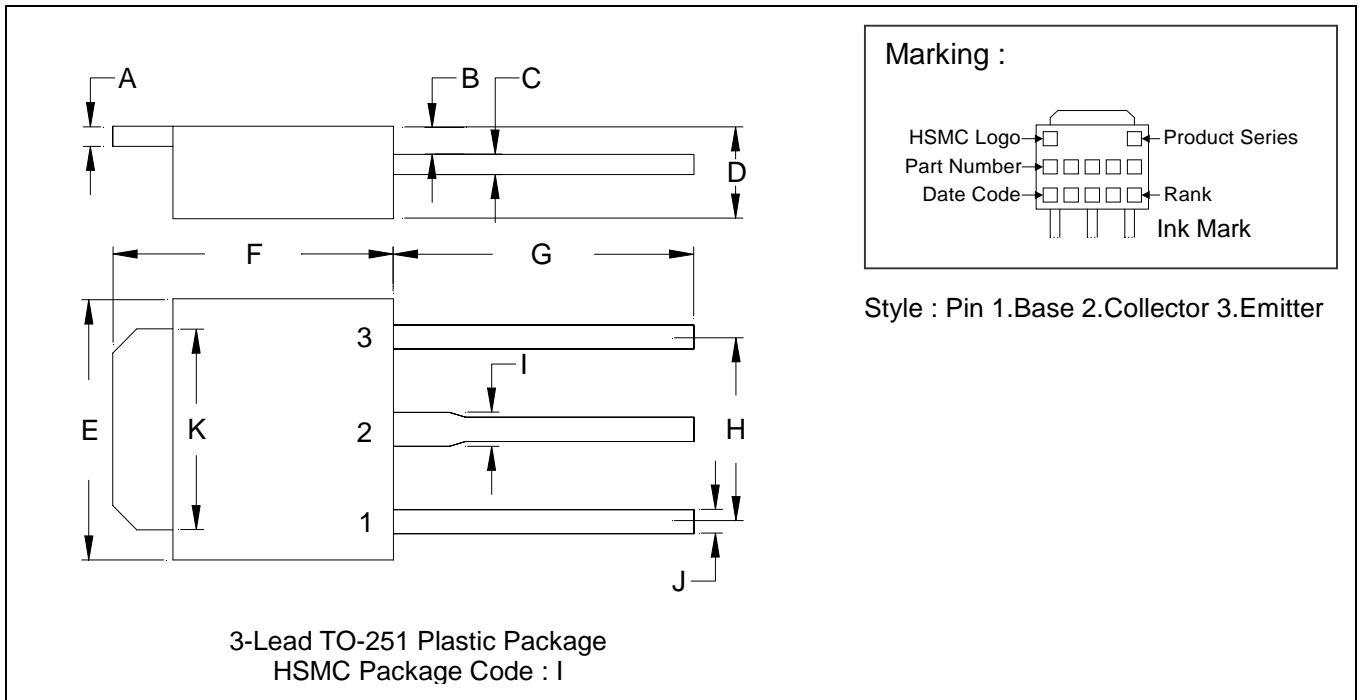


Characteristics Curve

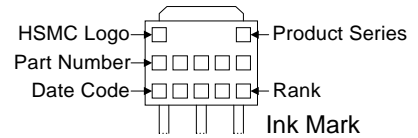




TO-251 Dimension



Marking :



Style : Pin 1.Base 2.Collector 3.Emitter

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0177	0.0217	0.45	0.55	G	0.2559	-	6.50	-
B	0.0354	0.0591	0.90	1.50	H	-	*0.1811	-	*4.60
C	0.0177	0.0236	0.45	0.60	I	-	0.0354	-	0.90
D	0.0866	0.0945	2.20	2.40	J	-	0.0315	-	0.80
E	0.2520	0.2677	6.40	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2677	0.2835	6.80	7.20					

- Notes : 1.Dimension and tolerance based on our Spec. dated May. 24,1995.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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